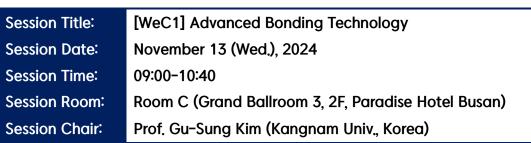
KOREAN INTERNATIONAL SEMICONDUCTOR CONFERENCE & EXHIBITION ON MANUFACTURING TECHNOLOGY 2024

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SAN



Paradise Hotel Busan & Grand Josun Busar (Haeundae Beach) | Busan, Korea



KISM 2024

[WeC1-1] [Plenary]

Surface Activated Bonding for 3D and Heterogeneous Integration Current Status and Future Prospects

Tadatomo Suga (Meisei Univ., Japan)

[WeC1-2] [Invited]

The Role of Hybrid Bonding in Modern Semiconductors

Thomas Glinsner (EV Group, Austria)

[WeC1-3] [Invited]

FINE Cut for HBM Wafer and FINE Forming for TVG of Glass Substrate

Seak-Joon Lee (ITI, Korea)



10:15-10:40

09:45-10:15

09:00-09:45